## Low Loss DuoPack: IGBT in TrenchStop ${ }^{\circledR}$ and Fieldstop technology with soft, fast recovery anti-parallel Emitter Controlled HE diode

- Approx. 1.0V reduced $\mathrm{V}_{\mathrm{CE} \text { (sat) }}$ and 0.5 V reduced $\mathrm{V}_{\mathrm{F}}$ compared to BUP314D
- Short circuit withstand time $-10 \mu \mathrm{~s}$
- Designed for :

- Frequency Converters
- Uninterrupted Power Supply
- TrenchStop ${ }^{\circledR}$ and Fieldstop technology for 1200 V applications offers :
- very tight parameter distribution
- high ruggedness, temperature stable behavior

- NPT technology offers easy parallel switching capability due to positive temperature coefficient in $\mathrm{V}_{\mathrm{CE} \text { (sat) }}$
- Low EMI
- Low Gate Charge
- Very soft, fast recovery anti-parallel Emitter Controlled HE diode
- Qualified according to JEDEC ${ }^{1}$ for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models : http://www.infineon.com/igbt/

| Type | $V_{\text {CE }}$ | $I_{\mathrm{C}}$ | $V_{\text {CE(sat) }, T_{j}=25^{\circ} \mathrm{C}}$ | $T_{\mathrm{j}, \max }$ | Marking Code | Package |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| IKW25T120 | 1200 V | 25 A | 1.7 V | $150^{\circ} \mathrm{C}$ | K25T120 | PG-TO-247-3 |

Maximum Ratings

| Parameter | Symbol | Value | Unit |
| :---: | :---: | :---: | :---: |
| Collector-emitter voltage | $V_{\text {CE }}$ | 1200 | V |
| DC collector current $\begin{aligned} & T_{\mathrm{C}}=25^{\circ} \mathrm{C} \\ & T_{\mathrm{C}}=100^{\circ} \mathrm{C} \end{aligned}$ | $I_{C}$ | $\begin{aligned} & 50 \\ & 25 \end{aligned}$ | A |
| Pulsed collector current, $t_{\mathrm{p}}$ limited by $T_{\text {jmax }}$ | $I_{\text {Cpuls }}$ | 75 |  |
| Turn off safe operating area $V_{\mathrm{CE}} \leq 1200 \mathrm{~V}, T_{\mathrm{j}} \leq 150^{\circ} \mathrm{C}$ | - | 75 |  |
| Diode forward current $\begin{aligned} & T_{\mathrm{C}}=25^{\circ} \mathrm{C} \\ & T_{\mathrm{C}}=100^{\circ} \mathrm{C} \end{aligned}$ | $I_{\text {F }}$ | $\begin{aligned} & 50 \\ & 25 \end{aligned}$ |  |
| Diode pulsed current, $t_{\mathrm{p}}$ limited by $T_{\text {jmax }}$ | $I_{\text {Fpuls }}$ | 75 |  |
| Gate-emitter voltage | $V_{\text {GE }}$ | $\pm 20$ | V |
| Short circuit withstand time ${ }^{2)}$ $V_{\mathrm{GE}}=15 \mathrm{~V}, V_{\mathrm{CC}} \leq 1200 \mathrm{~V}, T_{\mathrm{j}} \leq 150^{\circ} \mathrm{C}$ | $t_{\text {Sc }}$ | 10 | $\mu \mathrm{S}$ |
| Power dissipation $T_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | $P_{\text {tot }}$ | 190 | W |
| Operating junction temperature | $T_{\mathrm{j}}$ | -40...+150 | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | $T_{\text {stg }}$ | $-55 \ldots+150$ |  |

[^0]| Soldering temperature, 1.6 mm (0.063 in.) from case for 10 s |
| :--- |

Thermal Resistance

| Parameter | Symbol | Conditions | Max. Value | Unit |
| :--- | :--- | :---: | :---: | :---: |
| Characteristic <br> IGBT thermal resistance, <br> junction - case |  |  |  |  |
| thJC <br> Diode thermal resistance, <br> junction - case | $R_{\mathrm{thJCD}}$ |  | 0.65 | K/W |
| Thermal resistance, <br> junction - ambient | $R_{\mathrm{thJA}}$ |  | 1.0 |  |

Electrical Characteristic, at $T_{\mathrm{j}}=25^{\circ} \mathrm{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | min. | typ. | max. |  |
| Static Characteristic |  |  |  |  |  |  |
| Collector-emitter breakdown voltage | $V_{\text {(bR)CES }}$ | $V_{\mathrm{GE}}=0 \mathrm{~V}, I_{\mathrm{C}}=500 \mu \mathrm{~A}$ | 1200 | - | - | V |
| Collector-emitter saturation voltage | $V_{\text {CE(sat) }}$ | $\begin{aligned} & V_{\mathrm{GE}}=15 \mathrm{~V}, I_{\mathrm{C}}=25 \mathrm{~A} \\ & T_{\mathrm{j}}=25^{\circ} \mathrm{C} \\ & T_{\mathrm{j}}=125^{\circ} \mathrm{C} \\ & T_{\mathrm{j}}=150^{\circ} \mathrm{C} \\ & \hline \end{aligned}$ |  | $\begin{aligned} & 1.7 \\ & 2.0 \\ & 2.2 \end{aligned}$ | $2.2$ |  |
| Diode forward voltage | $V_{F}$ | $\begin{aligned} & V_{\mathrm{GE}}=0 \mathrm{~V}, I_{\mathrm{F}}=25 \mathrm{~A} \\ & T_{\mathrm{j}}=25^{\circ} \mathrm{C} \\ & T_{\mathrm{j}}=125^{\circ} \mathrm{C} \\ & T_{\mathrm{j}}=150^{\circ} \mathrm{C} \\ & \hline \end{aligned}$ |  | $\begin{aligned} & 1.7 \\ & 1.7 \\ & 1.7 \end{aligned}$ | $2.2$ |  |
| Gate-emitter threshold voltage | $V_{G E(t h)}$ | $\begin{aligned} & I_{\mathrm{C}}=1 \mathrm{~mA}, \\ & V_{\mathrm{CE}}=V_{\mathrm{GE}} \end{aligned}$ | 5.0 | 5.8 | 6.5 |  |
| Zero gate voltage collector current | $I_{\text {CES }}$ | $\begin{aligned} & V_{\mathrm{CE}}=1200 \mathrm{~V}, \\ & V_{\mathrm{GE}}=0 \mathrm{~V} \\ & T_{\mathrm{j}}=25^{\circ} \mathrm{C} \\ & T_{\mathrm{j}}=150^{\circ} \mathrm{C} \end{aligned}$ |  | - | $\begin{gathered} 0.25 \\ 2.5 \end{gathered}$ | mA |
| Gate-emitter leakage current | $I_{\text {GES }}$ | $V_{\mathrm{CE}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{GE}}=20 \mathrm{~V}$ | - | - | 600 | nA |
| Transconductance | $g_{\text {fs }}$ | $V_{C E}=20 \mathrm{~V}, I_{\text {C }}=25 \mathrm{~A}$ | - | 16 | - | S |
| Integrated gate resistor | $R_{\text {Gint }}$ |  |  | 8 |  | $\Omega$ |

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| Dynamic Characteristic |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Input capacitance | $C_{\text {iss }}$ | $\begin{aligned} & V_{\mathrm{CE}}=25 \mathrm{~V}, \\ & V_{\mathrm{GE}}=0 \mathrm{~V}, \\ & f=1 \mathrm{MHz} \end{aligned}$ | - | 1860 | - | pF |
| Output capacitance | $C_{\text {oss }}$ |  | - | 96 | - |  |
| Reverse transfer capacitance | $C_{\text {rss }}$ |  | - | 82 | - |  |
| Gate charge | $Q_{\text {Gate }}$ | $\begin{aligned} & V_{\mathrm{CC}}=960 \mathrm{~V}, I_{\mathrm{C}}=25 \mathrm{~A} \\ & V_{\mathrm{GE}}=15 \mathrm{~V} \end{aligned}$ | - | 155 | - | nC |
| Internal emitter inductance measured 5 mm ( 0.197 in .) from case | $L_{E}$ |  | - | 13 | - | nH |
| Short circuit collector current ${ }^{11}$ | $I_{\text {C(SC) }}$ | $\begin{aligned} & V_{\mathrm{GEE}}=15 \mathrm{~V}, t_{\mathrm{SC}} \leq 10 \mu \mathrm{~s} \\ & V_{\mathrm{CC}}=600 \mathrm{~V}, \\ & T_{\mathrm{j}}=25^{\circ} \mathrm{C} \end{aligned}$ | - | 150 | - | A |

Switching Characteristic, Inductive Load, at $T_{\mathrm{j}}=25^{\circ} \mathrm{C}$

| Parameter | Symbol | Conditions | Value |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | min. | typ. | max. |  |
| IGBT Characteristic |  |  |  |  |  |  |
| Turn-on delay time | $t_{\text {d }(\text { on) }}$ | $\begin{aligned} & T_{\mathrm{j}}=25^{\circ} \mathrm{C}, \\ & V_{\mathrm{CC}}=600 \mathrm{~V}, I_{\mathrm{C}}=25 \mathrm{~A} \\ & V_{\mathrm{GE}}=0 / 15 \mathrm{~V}, \\ & R_{\mathrm{G}}=22 \Omega, \\ & L_{\sigma^{2)}}{ }^{2)}=180 \mathrm{nH}, \\ & C_{\sigma}{ }^{2)}=39 \mathrm{pF} . \end{aligned}$ <br> Energy losses include "tail" and diode reverse recovery. | - | 50 | - | ns |
| Rise time | $t_{r}$ |  | - | 30 | - |  |
| Turn-off delay time | $t_{\text {d (off) }}$ |  | - | 560 | - |  |
| Fall time | $t_{\text {f }}$ |  | - | 70 | - |  |
| Turn-on energy | $E_{\text {on }}$ |  | - | 2.0 | - | mJ |
| Turn-off energy | $E_{\text {off }}$ |  | - | 2.2 | - |  |
| Total switching energy | $E_{\text {ts }}$ |  | - | 4.2 | - |  |


| Anti-Parallel Diode Characteristic |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Diode reverse recovery time | $t_{\text {rr }}$ | $\begin{aligned} & T_{\mathrm{j}}=25^{\circ} \mathrm{C}, \\ & V_{\mathrm{R}}=600 \mathrm{~V}, I_{\mathrm{F}}=25 \mathrm{~A}, \\ & d i_{\mathrm{F}} / d t=800 \mathrm{~A} / \mu \mathrm{s} \end{aligned}$ | - | 200 |  | ns |
| Diode reverse recovery charge | $Q_{\mathrm{rr}}$ |  | - | 2.3 |  | $\mu \mathrm{C}$ |
| Diode peak reverse recovery current | $I_{\text {rrm }}$ |  | - | 21 |  | A |
| Diode peak rate of fall of reverse recovery current during $t_{\mathrm{b}}$ | $d i_{\text {rr }} / d t$ |  |  | 390 |  | A/ $\mu \mathrm{s}$ |

[^1]Switching Characteristic, Inductive Load, at $T_{\mathrm{j}}=150^{\circ} \mathrm{C}$

| Parameter | Symbol | Conditions | Value |  |  | Unit |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | typ. | max. |  |  |

IGBT Characteristic

| Turn-on delay time | $t_{\text {d }(\text { on })}$ | $\begin{aligned} & T_{\mathrm{j}}=150^{\circ} \mathrm{C} \\ & V_{\mathrm{CC}}=600 \mathrm{~V}, I_{\mathrm{C}}=25 \mathrm{~A}, \\ & V_{\mathrm{GE}}=0 / 15 \mathrm{~V}, \\ & R_{\mathrm{G}}=22 \Omega, \\ & L_{\sigma}{ }^{1}=180 \mathrm{nH}, \\ & \underline{C}_{\sigma}{ }^{1)}=39 \mathrm{pF} \end{aligned}$ <br> Energy losses include "tail" and diode reverse recovery. | - | 50 | - | ns |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Rise time | $t_{\mathrm{r}}$ |  | - | 32 | - |  |
| Turn-off delay time | $t_{\text {d ( off) }}$ |  | - | 660 | - |  |
| Fall time | $t_{\mathrm{f}}$ |  | - | 130 | - |  |
| Turn-on energy | $E_{\text {on }}$ |  | - | 3.0 | - | mJ |
| Turn-off energy | $E_{\text {off }}$ |  | - | 4.0 | - |  |
| Total switching energy | $E_{\text {ts }}$ |  | - | 7.0 | - |  |

## Anti-Parallel Diode Characteristic

| Diode reverse recovery time | $t_{\text {rr }}$ | $\begin{aligned} & T_{\mathrm{j}}=150^{\circ} \mathrm{C} \\ & V_{\mathrm{R}}=600 \mathrm{~V}, I_{\mathrm{F}}=25 \mathrm{~A}, \\ & d i_{\mathrm{F}} / d t=800 \mathrm{~A} / \mu \mathrm{s} \end{aligned}$ | - | 320 | - | ns |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Diode reverse recovery charge | $Q_{\text {rr }}$ |  | - | 5.2 | - | $\mu \mathrm{C}$ |
| Diode peak reverse recovery current | $I_{\text {rrm }}$ |  | - | 29 | - | A |
| Diode peak rate of fall of reverse recovery current during $t_{\mathrm{b}}$ | $d i_{\text {rr }} / d t$ |  | - | 320 |  | A/ $\mu \mathrm{s}$ |

${ }^{1)}$ Leakage inductance $L_{\sigma}$ and Stray capacity $C_{\sigma}$ due to dynamic test circuit in Figure $E$.


Figure 1. Collector current as a function of switching frequency
$\left(T_{\mathrm{j}} \leq 150^{\circ} \mathrm{C}, D=0.5, V_{\mathrm{CE}}=600 \mathrm{~V}\right.$, $V_{\mathrm{GE}}=0 /+15 \mathrm{~V}, R_{\mathrm{G}}=22 \Omega$ )

$T_{\mathrm{C}}$, CASE TEMPERATURE
Figure 3. Power dissipation as a function of case temperature
( $T_{j} \leq 150^{\circ} \mathrm{C}$ )


Figure 2. Safe operating area
( $D=0, T_{\mathrm{C}}=25^{\circ} \mathrm{C}$,
$\left.T_{\mathrm{j}} \leq 150^{\circ} \mathrm{C} ; \mathrm{V}_{\mathrm{GE}}=15 \mathrm{~V}\right)$

$T_{\mathrm{C}}$, CASE TEMPERATURE
Figure 4. Collector current as a function of case temperature
$\left(V_{G E} \geq 15 \mathrm{~V}, T_{j} \leq 150^{\circ} \mathrm{C}\right.$ )


Figure 5. Typical output characteristic ( $T_{\mathrm{j}}=25^{\circ} \mathrm{C}$ )

$V_{\mathrm{GE}}$, GATE-EMItTER VOLTAGE
Figure 7. Typical transfer characteristic ( $\mathrm{V}_{\mathrm{CE}}=20 \mathrm{~V}$ )


Figure 6. Typical output characteristic $\left(T_{j}=150^{\circ} \mathrm{C}\right)$


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
( $V_{G E}=15 \mathrm{~V}$ )


Figure 9. Typical switching times as a function of collector current (inductive load, $T_{\mathrm{J}}=150^{\circ} \mathrm{C}$, $V_{\mathrm{CE}}=600 \mathrm{~V}, \mathrm{~V}_{\mathrm{GE}}=0 / 15 \mathrm{~V}, R_{\mathrm{G}}=22 \Omega$, Dynamic test circuit in Figure E)


Figure 10. Typical switching times as a function of gate resistor
(inductive load, $T_{\mathrm{J}}=150^{\circ} \mathrm{C}$,
$V_{\mathrm{CE}}=600 \mathrm{~V}, \mathrm{~V}_{\mathrm{GE}}=0 / 15 \mathrm{~V}, I_{\mathrm{C}}=25 \mathrm{~A}$,
Dynamic test circuit in Figure E)

$T_{\mathrm{J}}$, JUNCTION TEMPERATURE
Figure 11. Typical switching times as a function of junction temperature (inductive load, $V_{\mathrm{CE}}=600 \mathrm{~V}$,
$\mathrm{V}_{\mathrm{GE}}=0 / 15 \mathrm{~V}, I_{\mathrm{C}}=25 \mathrm{~A}, R_{\mathrm{G}}=22 \Omega$,
Dynamic test circuit in Figure E)


Figure 12. Gate-emitter threshold voltage as a function of junction temperature $\left(I_{\mathrm{C}}=1.0 \mathrm{~mA}\right)$

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Figure 13. Typical switching energy losses as a function of collector current (inductive load, $T_{\mathrm{J}}=150^{\circ} \mathrm{C}$,
$V_{\text {CE }}=600 \mathrm{~V}, \mathrm{~V}_{\mathrm{GE}}=0 / 15 \mathrm{~V}, R_{\mathrm{G}}=22 \Omega$, Dynamic test circuit in Figure E)

$T_{\mathrm{J}}$, JUNCTION TEMPERATURE
Figure 15. Typical switching energy losses as a function of junction temperature
(inductive load, $V_{\text {CE }}=600 \mathrm{~V}$,
$V_{G E}=0 / 15 \mathrm{~V}, I_{\mathrm{C}}=25 \mathrm{~A}, R_{\mathrm{G}}=22 \Omega$,
Dynamic test circuit in Figure E)


Figure 14. Typical switching energy losses as a function of gate resistor (inductive load, $T_{J}=150^{\circ} \mathrm{C}$,
$V_{\text {CE }}=600 \mathrm{~V}, \mathrm{~V}_{\mathrm{GE}}=0 / 15 \mathrm{~V}, \mathrm{I}_{\mathrm{C}}=25 \mathrm{~A}$,
Dynamic test circuit in Figure E)

$V_{C E}$, COLLECTOR-EMITTER VOLTAGE
Figure 16. Typical switching energy losses as a function of collector emitter voltage
(inductive load, $T_{J}=150^{\circ} \mathrm{C}$
$V_{G E}=0 / 15 \mathrm{~V}, I_{\mathrm{C}}=25 \mathrm{~A}, R_{\mathrm{G}}=22 \Omega$,
Dynamic test circuit in Figure E)


Figure 17. Typical gate charge
( $I_{\mathrm{c}}=25 \mathrm{~A}$ )

$V_{\text {GE }}$, GATE-EMITTETR VOLTAGE
Figure 19. Short circuit withstand time as a function of gate-emitter voltage ( $V_{\text {CE }}=600 \mathrm{~V}$, start at $T_{\mathrm{J}}=25^{\circ} \mathrm{C}$ )


Figure 18. Typical capacitance as a function of collector-emitter voltage
( $V_{G E}=0 \mathrm{~V}, f=1 \mathrm{MHz}$ )


Figure 20. Typical short circuit collector current as a function of gateemitter voltage
$\left(V_{\mathrm{CE}} \leq 600 \mathrm{~V}, T_{\mathrm{j}} \leq 150^{\circ} \mathrm{C}\right)$

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Figure 21. Typical turn on behavior
$\left(\mathrm{V}_{\mathrm{GE}}=0 / 15 \mathrm{~V}, R_{\mathrm{G}}=22 \Omega, T_{\mathrm{j}}=150^{\circ} \mathrm{C}\right.$, Dynamic test circuit in Figure E)


Figure 23. IGBT transient thermal resistance ( $D=t_{\mathrm{p}} / T$ )


Figure 22. Typical turn off behavior
( $\mathrm{V}_{\mathrm{GE}}=15 / \mathrm{OV}, R_{\mathrm{G}}=22 \Omega, T_{\mathrm{j}}=150^{\circ} \mathrm{C}$,
Dynamic test circuit in Figure E)


Figure 24. Diode transient thermal impedance as a function of pulse width
( $D=t_{\mathrm{P}} / T$ )


Figure 23. Typical reverse recovery time as a function of diode current slope ( $V_{R}=600 \mathrm{~V}, l_{F}=25 \mathrm{~A}$,
Dynamic test circuit in Figure E)


Figure 24. Typical reverse recovery charge as a function of diode current slope
( $V_{R}=600 \mathrm{~V}, l_{F}=25 \mathrm{~A}$,
Dynamic test circuit in Figure E)

$d i_{\mathrm{F}} / d t$, DIODE CURRENT SLOPE
Figure 25. Typical reverse recovery current as a function of diode current slope
( $V_{R}=600 \mathrm{~V}, l_{F}=25 \mathrm{~A}$,
Dynamic test circuit in Figure E)

$d i_{F} / d t$, DIODE CURRENT SLOPE
Figure 26. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope ( $V_{R}=600 \mathrm{~V}, I_{F}=25 \mathrm{~A}$,
Dynamic test circuit in Figure E)


Figure 27. Typical diode forward current as a function of forward voltage


Figure 28. Typical diode forward voltage as a function of junction temperature

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| DEM | MILLIMETERS |  | INCHES |  |
| :---: | :---: | :---: | :---: | :---: |
|  | MIN | MAX | MIN | MAX |
| A | 4.83 | 5.21 | 0.190 | 0.205 |
| A1 | 2.27 | 2.54 | 0.089 | 0.100 |
| A2 | 1.85 | 2.16 | 0.073 | 0.085 |
| b | 1.07 | 1.33 | 0.042 | 0.052 |
| b1 | 1.90 | 2.41 | 0.075 | 0.095 |
| b2 | 1.90 | 2.16 | 0.075 | 0,085 |
| b3 | 2.87 | 3.38 | 0.113 | 0.133 |
| b4 | 2.87 | 3.13 | 0.113 | 0.123 |
| $c$ | 0.55 | 0.68 | 0.022 | 0.027 |
| D | 20,80 | 21.10 | 0.819 | 0.831 |
| D1 | 16.25 | 17.65 | 0.840 | 0.895 |
| D2 | 0.95 | 1.35 | 0.837 | 0.053 |
| E | 15.70 | 16.13 | 0.818 | 0.835 |
| E1 | 13.10 | 14.15 | 0.516 | 0.557 |
| E2 | 3.68 | 5.10 | 0.145 | 0.201 |
| E3 | 1.00 | 2.60 | 0.039 | 0.102 |
| e | 5.44 (BSC) |  | 0.214 (BSC) |  |
| N | 3 |  | 3 |  |
| L | 19.80 | 20.32 | 0.780 | 0.800 |
| 11 | 4.10 | 4.47 | 0.161 | 0.176 |
| sp | 3.50 | 3.70 | 0.138 | 0.146 |
| Q | 5.49 | 6.00 | 0.216 | 0.236 |
| S | 6.04 | 6.30 | 0.238 | 0.248 |


| DOCUMENT NO. <br> Z8BOOOO3327 |
| :---: |
| SCALE |
| EUROPEAN PROJECTION |
| ISSUE DATE |
| OSOOT-2010 |
| REVISION |
| OS |



Figure A. Definition of switching times


Figure B. Definition of switching losses


Figure C. Definition of diodes switching characteristics


Figure D. Thermal equivalent circuit


Figure E. Dynamic test circuit Leakage inductance $L_{\sigma}=180 \mathrm{nH}$ and Stray capacity $C_{\sigma}=39 \mathrm{pF}$.

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[^0]:    ${ }^{1}$ J-STD-020 and JESD-022
    ${ }^{2)}$ Allowed number of short circuits: $<1000$; time between short circuits: $>1$ s.

[^1]:    ${ }^{1)}$ Allowed number of short circuits: $<1000$; time between short circuits: $>1 \mathrm{~s}$.
    ${ }^{2}$ ) Leakage inductance $L_{\sigma}$ and Stray capacity $C_{\sigma}$ due to dynamic test circuit in Figure $E$.

